

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MASATO HIDAKA	12/26/2018
RECEIVING PARTY DATA	
Name:	SMK CO., LTD.
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City:	SAGAMIHARA-SHI, KANAGAWA
State/Country:	JAPAN
Postal Code:	252-0152
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	29674975
CORRESPONDENCE DATA	
Fax Number:	
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ATTORNEY DOCKET NUMBER:	SMK-USD37014
NAME OF SUBMITTER:	MOTOKO OSHINO
SIGNATURE:	/Motoko Oshino/
DATE SIGNED:	12/27/2018
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 1	
source=SMK-USD37014_DeclarationAssignment#page1.tif	

COMBINED DECLARATION and ASSIGNMENT (37 CFR 1.63) FOR UTILITY OR
DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76)

Title of
Invention

Welding Electrode Tip

As the below named inventor, I hereby declare that:

This declaration
is directed to:



The attached application, or



United States application or PCT international application number _____
filed on _____.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the
application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18
U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

I have reviewed and understand the contents of the application and am aware of the duty to disclose to the
US Patent and Trademark Office all information known to me to be material to patentability as defined in
37 C.F.R. § 1.56.

ASSIGNMENT

For good and valuable consideration, the receipt, sufficiency and adequacy of which are hereby
acknowledged, I hereby assign and transfer to SMK CO., LTD., having a principal place of business at
830-5 Ooi, Midori-ku, Sagami-hara-shi, Kanagawa 252-0152, JAPAN, and its successors, assigns, and
legal representatives, my entire right, title and interest in and to the invention listed above, together with
the Application, any and all Patents that might issue for the United States and all foreign countries
(including the right to claim priority under the terms of the International Convention and any other
relevant International Treaties and Arrangements from the aforesaid application), in and to any and all
improvements that are disclosed in the above-noted application, and in and to any reissues, renewals,
continuations, continuation-in-parts, divisionals or extensions thereof that have been or shall be filed in
the United States and all foreign countries on any of said improvements.

I agree that I will communicate to the assignee or its representatives any facts known to me respecting
said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional,
continuation, substitute, renewal, and reissue applications, execute all necessary assignment papers to
cause any and all Patents to be issued to the assignee, make all rightful oaths, and, generally do
everything possible to aid said assignee, its successors and assigns, to obtain and enforce proper
protection for said invention in the United States and in any and all foreign countries.

The undersigned hereby grants the firm of **United IP Counselors, LLC** the power to insert in this
Assignment any further identification which might be necessary or desirable to comply with the rules of
the U.S. Patent and Trademark Office for recordation of this Assignment.

LEGAL NAME OF INVENTOR (Given name FAMILY NAME)

Inventor: Masato HIDAKA

Date: December 26, 2018

Signature: Masato Hidaka

PATENT